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Abstract

Method for producing an integrated circuit with a rewiring device and corresponding integrated circuit

The present invention provides a method for producing an integrated circuit (23) with a rewiring device (18, 19), having the following steps: provision of a carrier device (10) with defined cutouts (11); application of at least one integrated circuit (14) upside down to the carrier device (10) in such a way that the defined cutouts (11) of the carrier device (10) are located above at least one connection device (15) of the integrated circuit (14); application of an insulation device (17) to that side of the carrier device (10) which is not covered by the integrated circuit (14), omitting the at least one connection device (15) in the cutout (11); application of the patterned rewiring device (18, 19) to the insulation device (17); application of a patterned solder resist device (20) to the patterned rewiring device (18, 19); and patterned application of solder balls (22) on sections (21) of the rewiring device (18) which are not covered by the patterned solder resist device (20). The present invention likewise provides such an apparatus.

Figure 11

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